DSC7003

Silicon NPN epitaxial planar type

For low frequency amplification Complementary to DSA7003

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

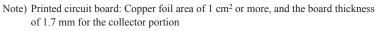
■ Marking Symbol: 5A

Packaging

 $DSC7003\times 0L \quad Embossed \ type \ (Thermo-compression \ sealing): 1000 \ pcs \ / \ reel \ (standard)$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	60	V
Collector-emitter voltage (Base open)	V _{CEO}	50	V
Emitter-base voltage (Collector open)	V _{EBO}	5	V
Collector current	I_{C}	1	A
Peak collector current	I _{CP}	1.5	A
Collector power dissipation	P _C	1	W
Junction temperature	T _j	150	°C
Operating ambient temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-55 to +150	°C



Absolute maximum rating without heat sink for P_{C} is $\ 0.5 \ \text{W}$

Unit: mm 4.5 1.6 0.41 <u>0.</u> 5 0.4 1.5 3.0 1: Base 2: Collector 3: Emitter Panasonic MiniP3-F2-B **JEITA** SC-62 Code TO-243

■ Electrical Characteristics $T_a = 25$ °C±3°C

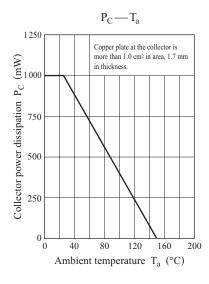
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu A, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V, } I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$	120		340	
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	50			_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.15	0.4	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.9	1.2	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 50 \text{ mA}$		170		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		10	20	pF

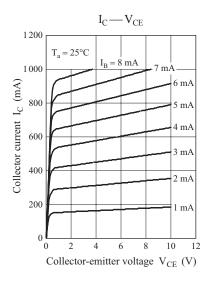
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

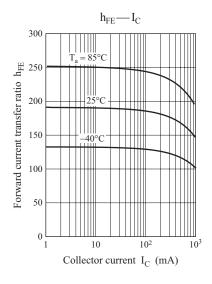
- 2. *1: Pulse measurement
 - *2: Rank classification

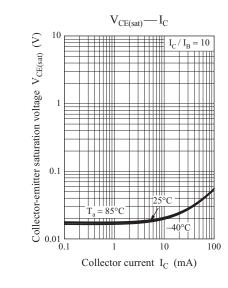
Code	R	S	0	
Rank	R	S	No-rank	
h_{FE1}	120 to 240	170 to 340	120 to 340	
Marking Symbol	5AR	5AS	5A	

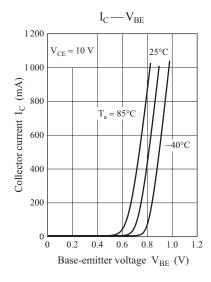
Product of no-rank is not classified and have no marking symbol for rank.

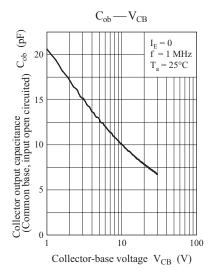


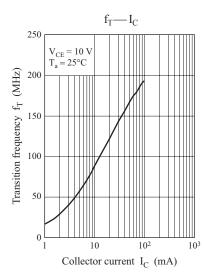








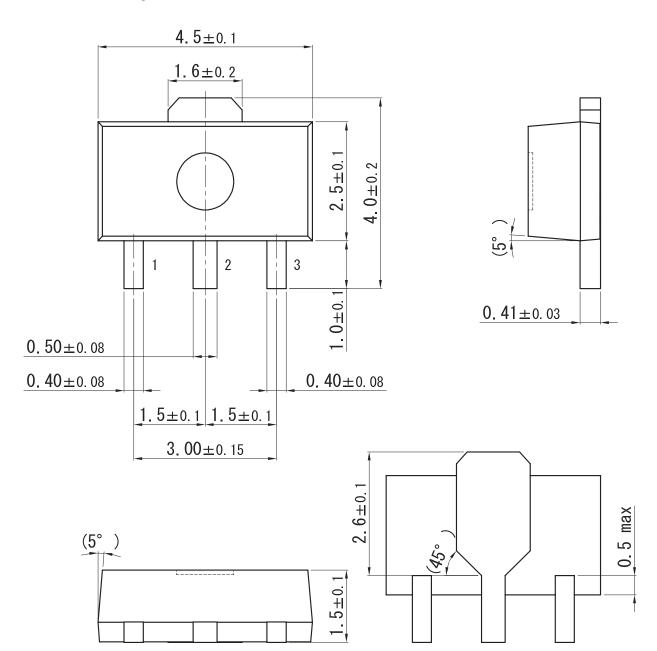




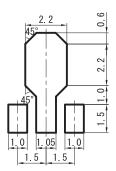
Ver. EED 2

MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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